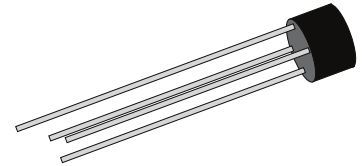


Features

- The plastic package carries underwriters laboratory flammability classification 94V-0
- Ideal for printed circuit boards
- Low reverse leakage
- High forward surge current capability
- High temperature soldering guaranteed:
 260°C/10 seconds, 0.375"(9.5mm) lead length
 5lbs (2.3kg) tension



W0B

Mechanical Data

- Case: Molded plastic body
- Terminals: Plated leads solderable per MIL-STD-750, method 2026
- Polarity: Polarity symbols marked on case
- Mounting Position: Any
- Weight: 0.042 ounce 1.2 grams

Absolute Maximum Ratings and Electrical Characteristics

(T_A=25°C unless otherwise noted)

Parameter	Symbol	W005G	W01G	W02G	W04G	W06G	W08G	W10G	Units
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Output Rectified Current at T _A =25°C ²	I _(AV)	1.5							A
Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load (JEDEC Method)	I _{FSM}	50							A
Rating for Fusing (t<8.3ms)	I ² t	10							A ² s
Maximum Instantaneous Forward Voltage Drop Per Bridge Element at 1.0A	V _F	1.0							V
Maximum DC Reverse Current at Rated DC Blocking Voltage (T _A =25°C)	I _R	10							μA
Maximum DC Reverse Current at Rated DC Blocking Voltage (T _A =100°C)		0.5							mA
Typical Junction Capacitance ¹	C _J	15							pF
Typical Thermal Resistance	R _{θJA}	40							°C/W
Operating Junction Temperature Range	T _J	-55 to +125							°C
Storage Temperature Range	T _{STG}	-55 to +150							°C

Note:

1. Measured at 1.0MHz and applied reverse voltage of 4.0V.
2. Unit mounted on P.C. board with 0.22" x 0.22" (5.5x5.5mm) copper pads, 0.375"(9.5mm) lead length.

Ratings and Characteristic Curves ($T_A=25^\circ\text{C}$ unless otherwise noted)

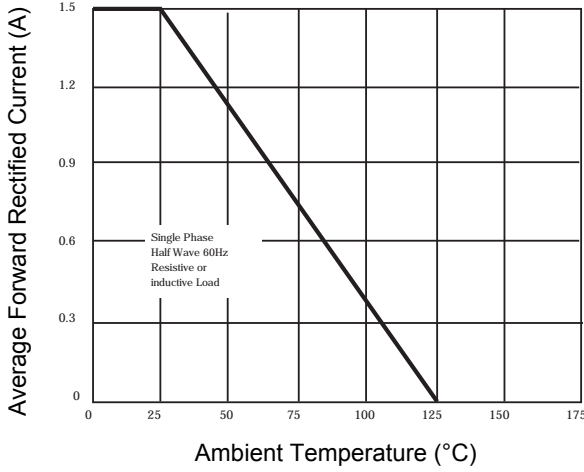


Figure 1. Forward Current Derating Curve

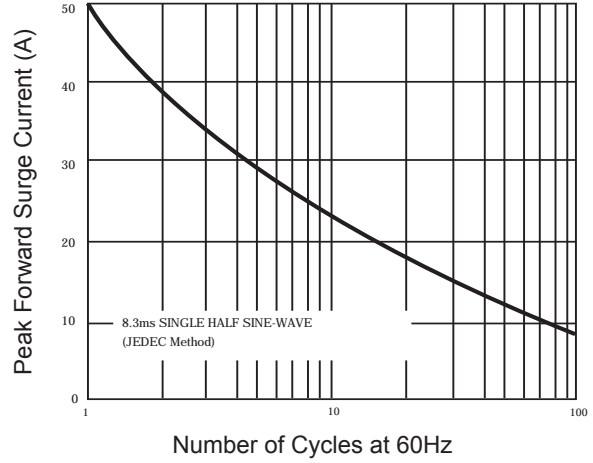


Figure 2. Maximum Non-Repetitive Peak Forward Surge Current

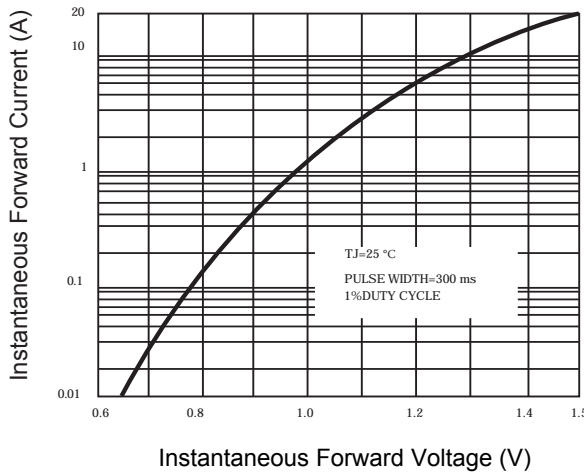


Figure 3. Typical Instantaneous Forward Characteristics

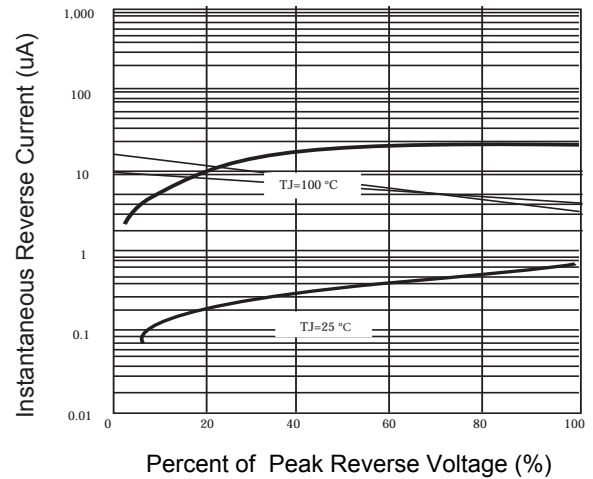


Figure 4. Typical Reverse Characteristics

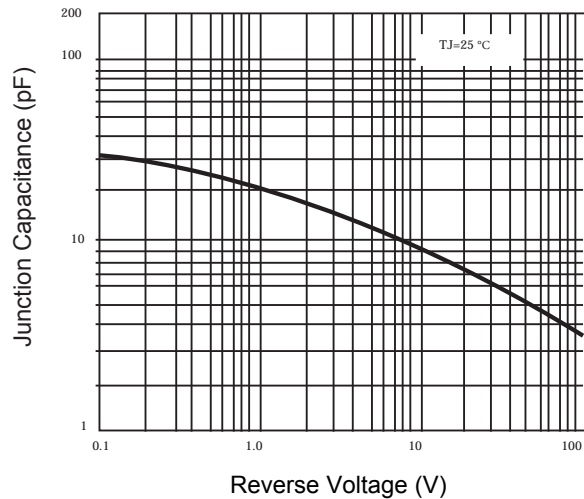


Figure 5. Typical Junction Capacitance

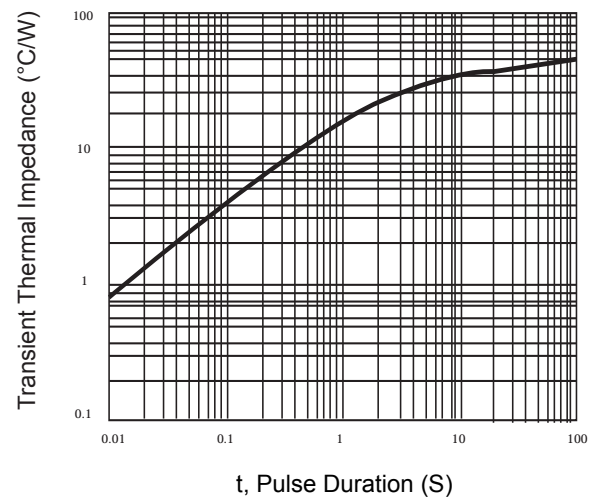
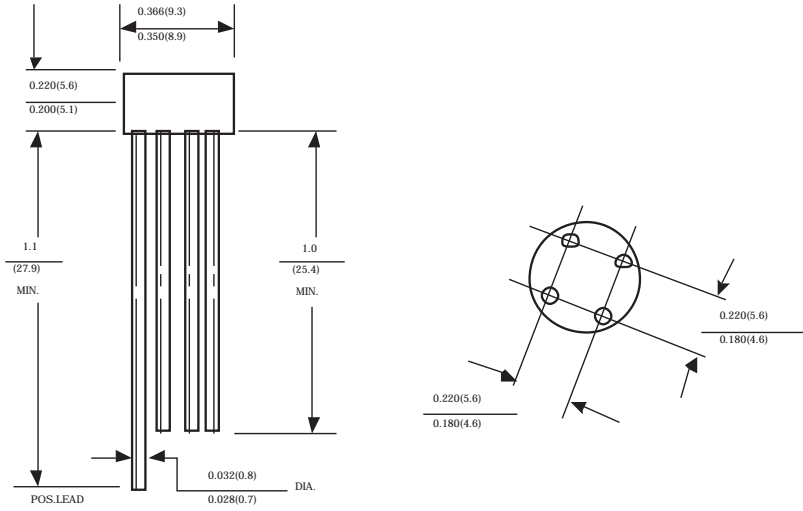


Figure 6. Typical Transient Thermal Impedance

Package Outline Dimensions (WOB)



Unit: Inches (Millimeters)